PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7927101

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TETSUYA UCHIDA	07/16/2020
RYOJI SUZUKI	07/28/2020
YOSHIHARU KUDOH	07/26/2020
HIROYUKI MORI	07/17/2020
HARUMI TANAKA	07/21/2020

RECEIVING PARTY DATA

Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
Street Address:	4-14-1 ASAHI-CHO
Internal Address:	ATSUGI-SHI
City:	KANAGAWA
State/Country:	JAPAN
Postal Code:	243-0014

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18309122

CORRESPONDENCE DATA

Fax Number: (303)863-0223

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 303-863-9700

Email: sony@sheridanross.com SHERIDAN ROSS P.C. **Correspondent Name:** Address Line 1: 1560 BROADWAY

Address Line 2: **SUITE 1200**

Address Line 4: DENVER, COLORADO 80202-5141

ATTORNEY DOCKET NUMBER:	6810-1295-DIV
NAME OF SUBMITTER: TROY D. CHRISTENSEN	
SIGNATURE:	/Troy D. Christensen/
DATE SIGNED:	04/28/2023
	This document serves as an Oath/Declaration (37 CFR 1.63).

PATENT

REEL: 063479 FRAME: 0744 507879971

Total Attachments: 5 source=Declarations_6810-1295-DIV#page1.tif source=Declarations_6810-1295-DIV#page2.tif source=Declarations_6810-1295-DIV#page3.tif

source=Declarations_6810-1295-DIV#page4.tif source=Declarations_6810-1295-DIV#page5.tif

Attorney Bocket No.: Sony Ref. No.: SP370200US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	SOLID-STATE IMAGING DEVICE AND ELECTRONIC APPARATUS	
As the below	numed inventor, I hereby declare that:	
This decleration is directed to:	The descent of the Constitution	
The aboveside	United States application or PCT international application number PCT/JP2018/041669 filed on 2018/11/09 entified application was made or authorized to be made by ms.	
WHEREAS.	I am the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION with offices at	
4-14-1 As	suhi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of	
acquiring all i	nterest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar an which may be granted therefor in the United States and in any and all foreign countries,	
legal represent in and to any and all procure of the Convention Radberes, and to United States Patent to said	FORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and tatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to correctly rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American elating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America o any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the and countries foreign thereto, and I bereby authorize and request the Commissioner of Patents to issue said United States Letters ASSIGNEE, as the assignee of the whole right, title and interest thereto:	
designer, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto:		
- аррикания зол	And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filling subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;	
sppucaum, sa	agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will e same in any interference or litigation related thereto:	
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknows than	rwledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of five (5) years, or both.	
LEGAL NAM	E OF INVENTOR	
Inventor:	TETSUYA UCHIDA Date: 2020/6η/16	
Signature:	TETSUYA UCHIDA	

Attorney Docket No.: Sony Ref. No.: SP370200US00

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As the below	named inventor, I hereby declare that:	
This declarati	on The attached application, or	
The above-ide	United States application or PCT international application number PCT/JP2018/041669 filed on 2018/11/09 entified application was made or authorized to be made by me.	
I believe that.	sm the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION	
4-14-1 As	rahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of	
acquiring all i	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar in which may be granted therefor in the United States and in any and all foreign countries:	
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto,		
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;		
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
I hereby acknown of more than	wiedge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by tine or imprisonment of five (5) years, or both.	
LEGAL NAM	E OF INVENTOR	
Inventor.	RYOH SUZUKI Date: 202の/0円/2分	
Signature:	Barin Sugalei	

Attorney Bocket No.: Sony Ret. No.: SP370200US00

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	Title of Invention	SOLID-STATE IMAGING DEVICE AND ELECTRONIC AT	PPARATUS
-	As the below	w named inventor, I hereby declare that:	
	This declaration is directed to:	226	
		United States application or PCT international application number PC filed on 2018/11/09	T/JP2018/041669
	The above-ide	identified application was made or authorized to be made by me	
	WHEREAS,	at I am the original inventor or an original joint inventor of a claimed invention in the applic SONY SEMICONDUCTOR SOLUTIONS CORPORATION	ation, with offices at
		Asam-cho, Atsugi-shi, Kanagawa, Japan hereinafter the description of t	referred to as ASSHONEED is desirous of
	legal protection	Il inserest in, to and under said invention, said application disclosing the invention and in, to tion which may be granted therefor in the United States and in any and all foreign countries	and under any Letters Patent or similar
	NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents. Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other henefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;		
	And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
	And I further agree to properly execute and deliver and without further remoneration, such necessary or desirable and lawful papers for application for foreign patents, for filling subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
	And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto.		
	And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.		
	I hereby acknown than	cnowledge that any willful false statement made in this declaration is punishable under 18 t in five (5) years, or both	U.S.C. 1001 by fine or imprisonment of
	LEGAL NAME OF INVENTOR		
		YOSHIHARU KUDOH Date:	holy 26,2020
	Signature:	Yoshiham Kaloh	
~	********		***************************************

Attorney Docket No.: Sony Ref. No.: SP370200US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

As the below named inventor. I flereby declare that: This declaration is directed to: United States application, or	Title of Invention	SOLID-STATE IMAGING DEVICE AND ELECTRONIC APPARATUS	
The attached application or PCT international application number PCT/IP2018/041669 filed on 2018/11/09 The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION	As the below	named inventor. I hereby declare that:	
The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION WHEREAS, SOLUTION AND AND AND AND AND AND AND AND AND AN		Contract to the second	
believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION 4.14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries. NOW THEREFORE, in consideration of the sum of One Dollar (31,90), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNIEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international sugrements which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto. And I further agree to execute all necessary or desirable and lawful future documents, including assignments in flavor of ASSIGNEE or its designee, as ASSIGNEE in the successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in		filed on 2018/11/09	
With offices at 4-14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinalter referred to as ASSIGNEE), is desirous of acquiring all interest in, in and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries. NOW THEREFORE, in consideration of the sum of One Dollar (\$1,90), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may graited for said invention, and in and to any and all priority rights and/or convention rights under the international Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Merdes, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, tile and interest theretor. And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE in rise successors, assigns and legal representatives may from time-to-time present to me and without further renumeration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto; as and ASSIGNEE in the patent of the patents. For filling subdivisions of said application for patent, and or, for obt		·	
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	LEGAL NAM	E OF INVENTOR	
Signature: HIROYUKL MORI	Inventor:	HIROYUKI MORI Date: 2020/07/19	
	Signature:	HIROYUKI MORI	

Attorney Bocket No.: Sony Ref. No.: SP370200US00

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As the below named inventor, I hereby declare that:		
This declaration is directed to: The attached application, or		
United States application or PCT international application number PCT/JP2018/041669 filed on 2018/11/09		
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at		
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NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the international Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignce of the whole right, title and interest thereto;		
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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
LEGAL NAME OF INVENTOR		
Inventor: HARUMI TANAKA Date: 2020 / 7 / 2/		
Signature: <u>Harumi Tanaka</u>		

PATENT REEL: 063479 FRAME: 0750

RECORDED: 04/28/2023